

Abstract

A device package has a conductive substrate with at least one mounting site, and an insulating substrate with a first side on the side of the conductive substrate with the one or more mounting sites. The insulating substrate has at least one aperture providing access between a second side of the insulating substrate and the one or more mounting sites. The insulating substrate has one or more signal paths on the second side that couple the one or more apertures to one or more contact sites disposed about the insulating substrate. A series of conductive tabs is coupled to corresponding contact sites.

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